Editorial

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Biographical notes: Dong-Wook Oh is Professor in the Department of Mechanical Engineering at Chosun University, South Korea. He received PhD in Mechanical Engineering from Seoul National University. Prior to joining Chosun University, he worked as a post-Doctoral researcher at the Department of Material Science and Engineering, University of Illinois at Urbana-Champaign, and a senior researcher at the Department of Advanced Thermal Systems, Korea Institute of Machinery and Materials. His current research is focused on thermal characterisation and application of thermally conductive composites.

Yeon Suk Choi received a PhD degree in Mechanical Engineering from Florida State University and currently is the Principal Researcher in the Division of Scientific Instrument at the Korea Basic Science Institute, South Korea. His research interests include the development of physical property measuring equipment, measurement and analysis of thermal property, heat and mass transfer at low temperature and superconducting magnet applications.

Joohyun Lee received a PhD degree in Mechanical Engineering from Stanford University and currently is the Principal Research Scientist in the Division of Interdisciplinary Materials Measurement Institute at the Korea Research Institute of Standards and Science, South Korea. His research interests are thermophysical properties measurements such as thermal conductivity and specific heat. The 23rd Korean Thermophysical Properties (KSTP) Conference was held in Korea Atomic Energy Research Institute (KAERI), Daejon, South Korea on 6 April, 2023. The conference was organised by Dr. Tae-Jin Park, KAERI with the support of members of KSTP. Numerous exciting recent advances in thermophysical property measurements were presented and fruitful discussions were made throughout technical sessions and social events.

This special issue is a collection of 10 papers that are revised and expanded from the original conference presentation. All papers are carefully selected and peer-reviewed by domestic and international reviewers. This issue covers aspects of thermal property measurements in nano/micro-scale and emerging advanced materials.

We would like to thank all the authors and reviewers for their professionalism and contribution to this special issue. Special gratitude should also be given to Dr. Lionel Vayssieres, Editor-in-Chief of the *International Journal of Nanotechnology*, for providing this wonderful opportunity.